

## C1210X369C2TACTU

Aliases (C1210X369C2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 3.6 pF, +/-0.25 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Packaging Specifications	
В	0.6mm +/-0.25mm
В	0.6mm + / 0.3Emm
S	1.5mm MIN
Т	0.78mm +/-0.20mm
W	2.6mm +/-0.3mm
_	5.5mm / 5. mm

Specifications	
Capacitance	3.6 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.25 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging Specifications		Capacitance Change v
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C ar Applied (TCC)
Packaging Quantity	4000	Dissipation Factor
		Asing Date

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